12 Phase Synchronous-Rectified Buck Controller for Next Generation CPU Core Power

General Description

The uP6208 12-phase PWM control IC provides a precision voltage regulation system for advanced microprocessors. It can work with Intel VR11/VR10 and AMD 5/6-bit VID table. The controller also includes programmable no-load offset and active voltage positioning functions to adjust the output voltage as a function of the load current, so it is optimally positioned for a load current transient. Continuous R_{DC} current sensing is used for load line programming and channel current balance. The uP6208 also provides accurate and reliable over current protection, over voltage protection and a delayed power good output. The uP6208 includes an I²C interface, allowing the controller to communicate with other devices over an I²C bus. Signals sent over this bus can command the uP6208 to adjust output voltage, switching frequency and operating phase number in different load current state.

Ordering Information

Order Number	Package Type	Remark
uP6208ALAM	LQFP7x7 - 64L	

Note: uPI products are compatible with the current IPC/JEDEC J-STD-020 and RoHS requirements. They are 100% matte tin (Sn) plating and suitable for use in SnPb or Pb-free soldering processes.
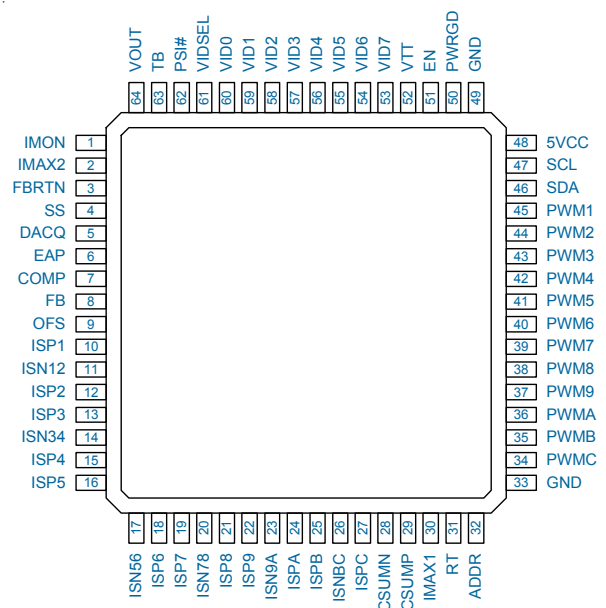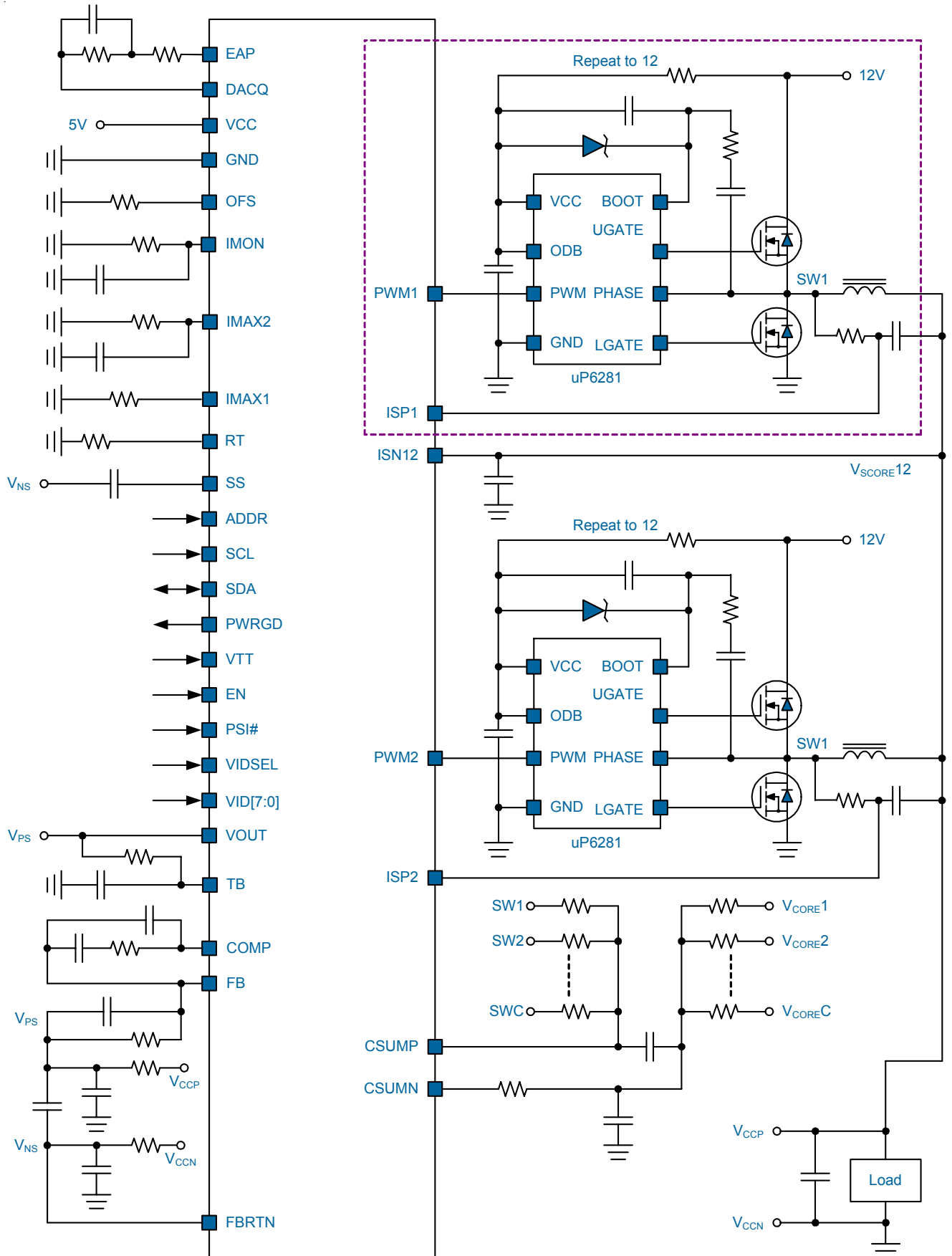
Features

☐ **Selectable 12/8-phase Operation by Hardware Setting**

☐ **Precision Core Voltage Regulation**

☐ **Differential Remote Voltage Sensing**

☐ **Adjustable Reference Voltage Offset**

☐ **Continuous Inductor R_{DC} Current Sensing**

☐ **I²C Interface**

　■ **Voltage Adjustment**

　■ **Switching Frequency Adjustment**

　■ **Operating Phase Number Adjustment**

☐ **Microprocessor VID Inputs**

　■ **8-Bit DAC**

　■ **Selectable between Intel VR11/10 and AMD**

　■ **5/6-bit DAC Tables**

☐ **Over-current Protection**

☐ **Over-voltage Protection**

☐ **Soft-Start**

☐ **Selectable Operation Frequency from 100kHz to 1.5MHz per Phase**

Applications

☐ **Desktop PC Core Power Supplies**

Pin Configuration

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Typical Application Circuit

No.	Name	Pin Function
1	IMON	**Output Current Indication.** Analog output representing total load current. Output current of IMON is proportional to total load current. Connect a resistor between IMON and GND then the voltage of IMON is proportional to total load current. A capacitor may be connected between IMON and GND also to adjust the response time of IMON. IMON voltage is clamped to be lower than VTT.
2	IMAX2	**Total Load Current OCP Setting Input.** Output current of IMAX2 is proportional to total load current. Connect a resistor between IMAX2 and GND then the voltage of IMAX2 is proportional to total load current. If IMAX2 voltage is higher than 1.2V, OCP will be triggered. Resistor between IMAX2 and GND can adjust OCP level. Capacitor between IMAX2 and GND can filter load current ripple to avoid OCP mis-trigger.
3	FBRTN	**Feedback Return.** VID DAC and error amplifier reference for remote sensing of the output voltage.
4	SS	**Soft Start.** A capacitor connected between SS and GND sets the soft start ramp-up time. Pull this pin to GND will shut down the controller.
5	DACQ	**DAC Output.**
6	EAP	**Non-Inverting Input of the Error Amplifier**. A resistor between EAP and the DACQ sets the load line.
7	COMP	**Compensation Output.** Error amplifier output and compensation point.
8	FB	**Feedback Pin.** Feedback input. Error amplifier inverting input for remote sensing of the output voltage. FB, COMP and output voltage are tied together through external R-C networks to compensate the regulator.
9	OFS	**Zero Current Offset.** Connect a resistor between OFS and GND to generate an offset voltage across the resistor between FB and output voltage. The offset current is generated via the external resistor and a precision internal voltage. For no offset, the OFS pin should be left unconnected.
10	ISP1	**Non-inverting Input of the Current Sensing GM Amplifier for Phase 1.** The pin is used for differentially sensing channel 1 output currents. The sensed current is used for channel current balancing and protection. Connect this pin to the node between the RC sense elements surrounding the inductor.
11	ISN12	**Inverting Input of the Current Sensing GM Amplifier for Phase1 and 2.** Common inverting input of channel 1 and channel 2 current sensing. Tie the pin to the midway of VCORE side of channel 1 and channel 2 sensing capacitor. The VCORE side of channel 1 inductor and channel 2 inductor should be placed as close as possible. The resistance between ISN12 to the VCORE side of inductor 1 and inductor 2 should be as equal as possible. PCB trace resistance should be taken into consideration.
12	ISP2	**Non-inverting Input of the Current Sensing GM Amplifier for Phase 2.** The pin is used for differentially sensing channel 2 output currents. The sensed current is used for channel current balancing and protection. Connect this pin to the node between the RC sense elements surrounding the inductor.
13	ISP3	**Non-inverting Input of the Current Sensing GM Amplifier for Phase 3.** The pin is used for differentially sensing channel 3 output currents. The sensed current is used for channel current balancing and protection. Connect this pin to the node between the RC sense elements surrounding the inductor.
14	ISN34	**Inverting Input of the Current Sensing GM Amplifier for Phase 3 and 4.** Function is the same as ISN12 except the respective channels are 3 and 4.

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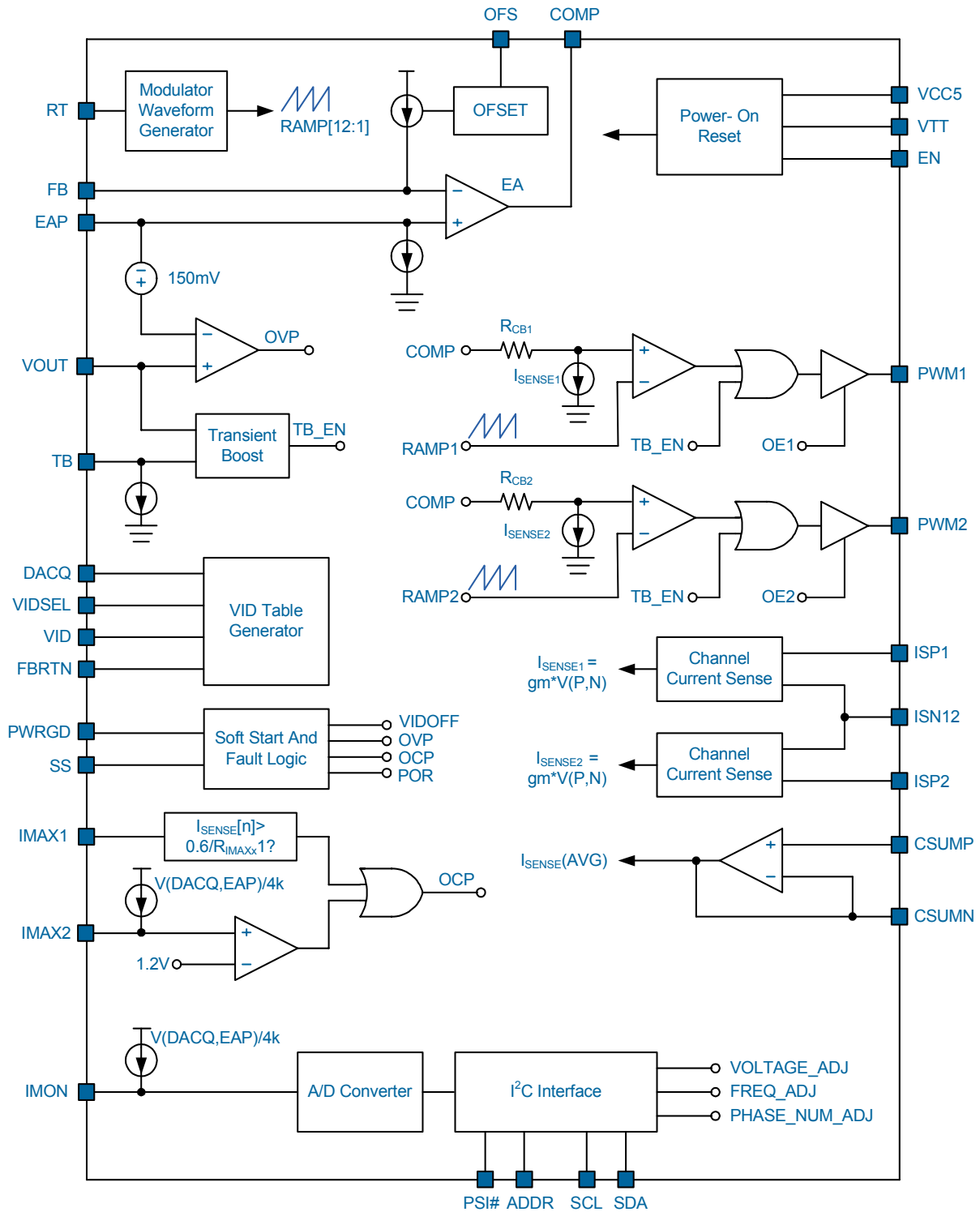| No.	Name	Pin Function
15	ISP4	**Non-inverting Input of the Current Sensing GM Amplifier for Phase 4.** The pin is used for differentially sensing channel 4 output currents. The sensed current is used for channel current balancing and protection. Connect this pin to the node between the RC sense elements surrounding the inductor.
16	ISP5	**Non-inverting Input of the Current Sensing GM Amplifier for Phase 5.** The pin is used for differentially sensing channel 5 output currents. The sensed current is used for channel current balancing and protection. Connect this pin to the node between the RC sense elements surrounding the inductor.
17	ISN56	**Inverting Input of the Current Sensing GM Amplifier for Phase 5 and 6.** Function is the same as ISN12 except the respective channels are 5 and 6.
18	ISP6	**Non-inverting Input of the Current Sensing GM Amplifier for Phase 6.** The pin is used for differentially sensing channel 6 output current. The sensed current is used for channel current balancing and protection. Connect this pin to the node between the RC sense elements surrounding the inductor.
19	ISP7	**Non-inverting Input of the Current Sensing GM Amplifier for Phase 7.** The pin is used for differentially sensing channel 7 output current. The sensed current is used for channel current balancing and protection. Connect this pin to the node between the RC sense elements surrounding the inductor.
20	ISN78	**Inverting Input of the Current Sensing GM Amplifier for Phase 7 and 8.** Function is the same as ISN12 except the respective channels are 7 and 8.
21	ISP8	**Non-inverting Input of the Current Sensing GM Amplifier for Phase 8**. The pin is used for differentially sensing channel 8 output current. The sensed current is used for channel current balancing and protection. Connect this pin to the node between the RC sense elements surrounding the inductor.
22	ISP9	**Non-inverting Input of the Current Sensing GM Amplifier for Phase 9.** The pin is used for differentially sensing channel 9 output current. The sensed current is used for channel current balancing and protection. Connect this pin to the node between the RC sense elements surrounding the inductor.
23	ISN9A	**Inverting Input of the Current Sensing GM Amplifier for Phase 9 and A.** Function is the same as ISN12 except the respective channels are 9 and A. Besides, connecting ISN9A to VCC will program the controller for 8-phase operation.
24	ISPA	**Non-inverting Input of the Current Sensing GM Amplifier for Phase A.** The pin is used for differentially sensing channel A output current. The sensed current is used for channel current balancing and protection. Connect this pin to the node between the RC sense elements surrounding the inductor.
25	ISPB	**Non-inverting Input of the Current Sensing GM Amplifier for Phase B.** The pin is used for differentially sensing channel B output current. The sensed current is used for channel current balancing and protection. Connect this pin to the node between the RC sense elements surrounding the inductor.
26	ISNBC	**Inverting Input of the Current Sensing GM Amplifier for Phase B and C.** Function is the same as ISN12 except the respective channels are B and C.
27	ISPC	**Non-inverting Input of the Current Sensing GM Amplifier for Phase C.** The pin is used for differentially sensing channel C output current. The sensed current is used for channel current balancing and protection. Connect this pin to the node between the RC sense elements surrounding the inductor.

Functional Pin Description

No.	Name	Pin Function
28	CSUMN	**Inverting Input of the Current Sensing Amplifier for Total Current.** Total load current sense inverting input. Connect a resistor between CSUMN and the VCORE side of all output inductors. The selected VCORE point should have equal resistance to the VCORE side of all inductors. PCB trace resistance should be taken into consideration.
29	CSUMP	**Non-inverting Input of the Current Sensing GM Amplifier for Total Current.** Channel current averaging node. Resistors from each switch node to this pin average the inductor currents on the capacitor between CSUMP and VCORE.
30	IMAX1	Connect a resistor between IMAX1 and GND to generate a reference current for channel current OCP. The reference current is generated via the external resistor and a precision internal voltage.
31	RT	**Switching Frequency Programming.** Connect a resistor from this pin to GND to set the switching frequency.
32	ADDR	**Address Selection for I²C Interface.** Connect a voltage divider from VCC to ADDR to GND to set the I²C address. The pin selects which of the three 8-bit Slave I²C addresses will be used by the controller. Connecting this pin to GND will choose address (1000_101x). Connecting this pin to VCC will choose address (1000_111x). Connecting this pin to VCC/2 will choose address (1000_110x).
33	GND	**Ground.** GND is the bias and reference ground for the IC.
34	PWMC	**PWM Output for Phase C.** Pulse width modulation output. Each output is connected to the input of external MOSFET driver such as the uP6281.
35	PWMB	**PWM Output for Phase B.** Pulse width modulation output. Each output is connected to the input of external MOSFET driver such as the uP6281.
36	PWMA	**PWM Output for Phase A.** Pulse width modulation output. Each output is connected to the input of external MOSFET driver such as the uP6281.
37	PWM9	**PWM Output for Phase 9.** Pulse width modulation output. Each output is connected to the input of external MOSFET driver such as the uP6281.
38	PWM8	**PWM Output for Phase 8.** Pulse width modulation output. Each output is connected to the input of external MOSFET driver such as the uP6281.
39	PWM7	**PWM Output for Phase 7.** Pulse width modulation output. Each output is connected to the input of external MOSFET driver such as the uP6281.
40	PWM6	**PWM Output for Phase 6.** Pulse width modulation output. Each output is connected to the input of external MOSFET driver such as the uP6281.
41	PWM5	**PWM Output for Phase 5.** Pulse width modulation output. Each output is connected to the input of external MOSFET driver such as the uP6281.
42	PWM4	**PWM Output for Phase 4.** Pulse width modulation output. Each output is connected to the input of external MOSFET driver such as the uP6281.
43	PWM3	**PWM Output for Phase 3.** Pulse width modulation output. Each output is connected to the input of external MOSFET driver such as the uP6281.
44	PWM2	**PWM Output for Phase 2.** Pulse width modulation output. Each output is connected to the input of external MOSFET driver such as the uP6281.
45	PWM1	**PWM Output for Phase 1.** Pulse width modulation output. Each output is connected to the input of external MOSFET driver such as the uP6281.

Functional Pin Description

No.	Name	Pin Function
46	SDA	**Data for I²C Interface.** Connect SDA to the bidirectional data line of the I²C bus.
47	SCL	**Clock for I²C Interface.** Connect SCL to the clock signal for the I²C bus.
48	5VCC	**Supply Input fo the IC.** Connect this pin to a 5V voltage source with RC filter. Voltage power supply of the IC. Connect this pin to a 5V supply and decouple using a 0.1uF ceramic capacitor.
49	GND	**Ground.**
50	PWRGD	**Power Good Indication.** This open-drain output is set to high impedance. Power good output. Open drain output that indicates the soft start process is complete and no fault happens.
51	EN	**Chip Enable.** Pulling low this pin disables the uP6208. Enable input of the controller. Voltage of this pin higher than 1.1V enables the controller. Lower than 1.0V disables the controller. It is recommended to use this pin to detect whether MOSFET driver power supply is ready.
52	VTT	**Enable input of the controller.** Voltage of this pin higher than 0.85V enables the controller. Lower than 0.75V disables the controller. It is recommended to use this pin to detect whether VTT power is ready.
53	VID7	**Bit 7 of DAC Input.** Voltage ID DAC inputs.
54	VID6	**Bit 6 of DAC Input.** Voltage ID DAC inputs.
55	VID5	**Bit 5 of DAC Input.** Voltage ID DAC inputs.
56	VID4	**Bit 4 of DAC Input.** Voltage ID DAC inputs.
57	VID3	**Bit 3 of DAC Input.** Voltage ID DAC inputs.
58	VID2	**Bit 2 of DAC Input.** Voltage ID DAC inputs.
59	VID1	**Bit 1 of DAC Input.** Voltage ID DAC inputs.
60	VID0	**Bit 0 of DAC Input.** Voltage ID DAC inputs.
61	VIDSEL	**VID Table Selection.** VR select input. Connect this pin to VTT(1.2V) to select the VR11 DAC table. Ground this pin to select the VR10 DAC table. Connect this pin to VCC(5V) to select AMD DAC table.
62	PSI#	**Power state indicator input from CPU.** PSI# is an active low signal, asserted when the CPU current is in the range of ~<25A. When PSI# goes low, controller will reduce the operating phase number to improve light load efficiency.
63	TB	**Transient Boost.** This pin along with the VOUT pin set the transient boost behavior. Transient boost. This pin along with the VOUT pin set the transient boost behavior.
64	VOUT	**Output voltage detection input.** Voltage of this pin is used for setting transient boost behavior and OVP detection.

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Functional Block Diagram

Functional Description

The uP6208 is a 12/8-phase, multimode (voltage control, current balance control, loadline control), fixed frequency PWM synchronous buck power converters. The internal VID DAC is designed for Intel VR11/VR10 and AMD 5/6-bit interface.
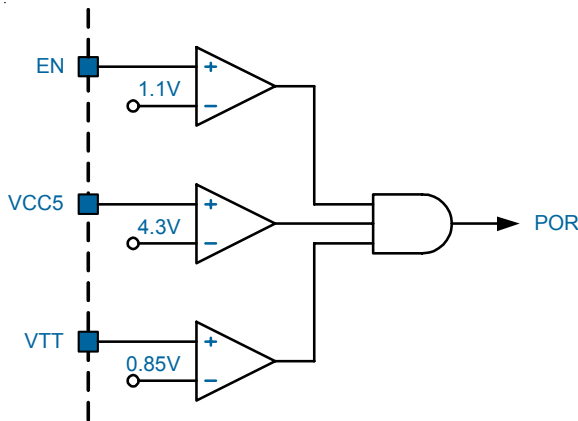
Power Ready Detection

Figure1. Circuit for Power Ready Detection

During start-up, the uP6208 will detect V_{CC5}, V_{TT} and EN. When V_{CC5} > 4.3V, V_{TT} > 0.85V and EN > 0.85V, POR (Power On Reset) will go high. POR is the internal signal to indicate all voltage powers are ready to let the uP6208 and the companioned MOSFET drivers to work properly. When POR = Low, the uP6208 will try to turn off both high side and low side MOSFETs.

Phase Detection

The number of operational phases is determined by the internal circuitry that monitors the ISN9A voltages during start up. Normally, the uP6208 operates as a 12-phase PWM controller. Pull ISN9A to V_{CC5} programs 8-phase operation. The uP6208 detects the voltage of ISN9A at POR rising edge. At the rising edge, the uP6208 detects whether the voltage of ISN9A is higher than V_{CC5} - 1V to decide how many phases should be active. Phase detection is only active during start up. When POR = High, the number of operational phases is determined and latched.

Phase Switching Frequency

The phase switching frequency of the the uP6208 is set by an external resistor connected between RT pin and GND. The frequency can be calculated as below and follows the graph in Figure 2.

$$F_{SW} = \frac{8.4G}{R_{RT} + 2k}$$
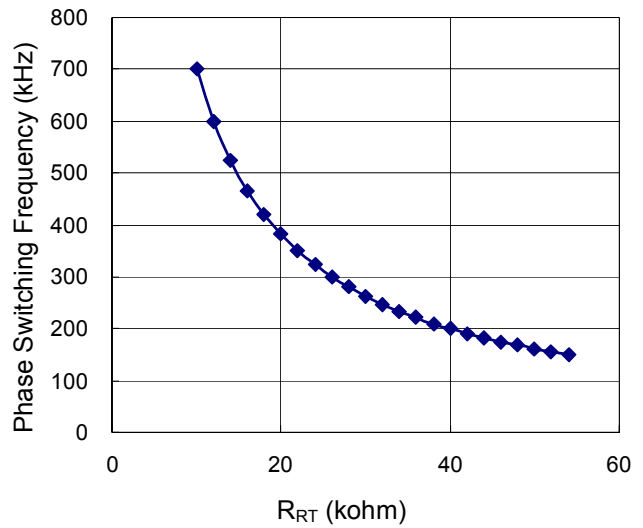
R_{RT}(kohm)	F_{SW}(kHz)		
10	700.0	32	247.1
12	600.0	34	233.3
14	525.0	36	221.1
16	466.7	38	210.0
18	420.0	40	200.0
20	381.8	42	190.9
22	350.0	44	182.6
24	323.1	46	175.0
26	300.0	48	168.0
28	280.0	50	161.5
30	262.5	52	155.6
		54	150.6

Figure2. Phase Switching Frequency vs R_{RT}

V_{DAC} Generator

The uP6208 builds a precise bandgap reference circuit inside. The output voltage of bandgap reference is 2.1V referred to FBRTN. In Figure 3, the uP6208 uses plural resistors to generate precise reference voltages ranging from 0.5V to 2.1V. All the voltages connect to a multiplexer (MUX). According to the VID inputs and I²C command, multiplexer outputs the selected voltage, V_{DAC}. Please be careful that all the voltage values in Figure 3 are referred to FBRTN.
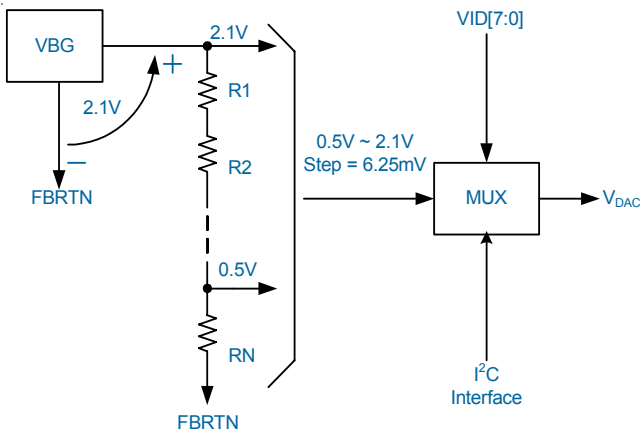
Figure3. V_{DAC} Generator Circuit

Soft Start

Output current of OPSS(I_{SS}) is limited within +/- 32uA (normal state) or +/- 320uA (VID OTF).
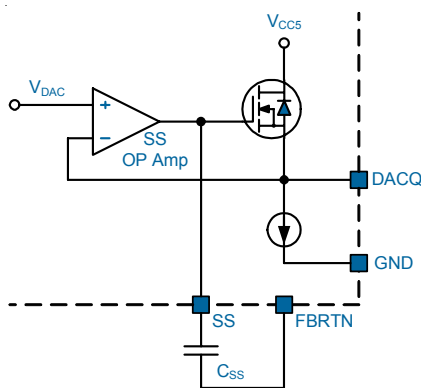

Figure 4. Circuit for Soft Start and Dynamic VID.

The V_{OUT} start-up time is set by a capacitor from the SS pin to FBRTN. In power_on_reset state (POR = Low), the SS pin is held at GND. After power_on_reset state (POR = High) and an extra delay 1600uS, V_{SS} and V_{DACQ} begin to rise till $V_{DACQ} = V_{BOOT}$. When $V_{DACQ} = V_{BOOT}$, the uP6208 stays in this state for 800uS waiting for valid VID code sent by CPU. After receiving the valid VID code, V_{OUT} continues ramping up or down to the voltage specified by VID code. The typical soft start waveform is shown in Figure 5.
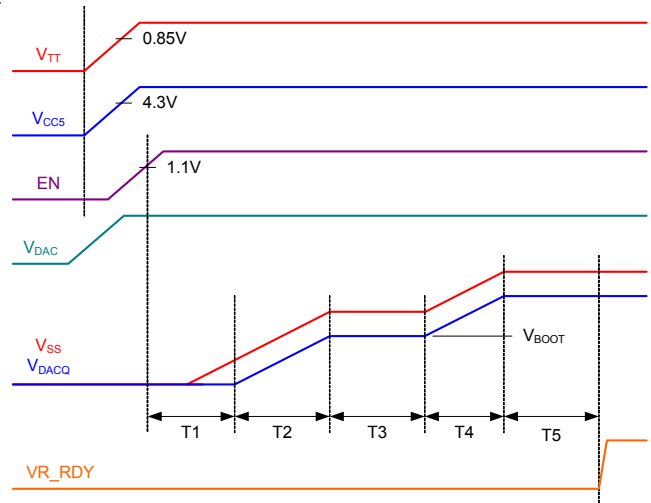
Figure 5. Soft Start Waveforms.

V_{OUT} will trace V_{EAP} which is the non-inverting input of error amplifier. T1 is the delay time from power_on_reset state to the beginning of V_{OUT} rising.

$$T1 \sim= 1600us + 0.7V \times C_{SS} / 32uA \qquad (1)$$

T2 is the soft start time from $V_{OUT} = 0$ to $V_{OUT} = V_{BOOT}$

$$T2 \sim= V_{BOOT} \times C_{SS} / 32uA \qquad (2)$$

T3 is the dwelling time for $V_{OUT} = V_{BOOT}$. T3 $\sim=$ 800us. T4 is the soft start time from $V_{OUT} = V_{BOOT}$ to $V_{OUT} = V_{VID.}$

$$T4 \sim= |V_{VID} - V_{BOOT}| \times C_{SS} / 32uA \qquad (3)$$

T5 is the power good delay time, T5 $\sim=$ 1600us.

Dynamic VID

The uP6208 can accept VID input changing while the controller is running. This allows the output voltage V_{OUT} to change while the DC/DC converter is running and supplying current to the load. This is commonly referred to as VID on-the-fly (OTF). A VID OTF may occur under either light or heavy load conditions. This change can be positive or negative. During VID OTF, V_{DAC} is a staircase waveform. In the uP6208, C_{SS} is also used to filter the V_{DAC}. By properly selecting C_{SS}, VID OTF performance can be improved.

Output Voltage Differential Sensing

The uP6208 uses differential sensing by a high gain low offset error amplifier as shown in Figure 6. The CPU voltage is sensed between the FB and FBRTN pins. A resistor R_{FB} connects FB pin and the positive remote sense pin of the CPU V_{CCP}. FBRTN pin connects to the negative remote sense pin of CPU V_{CCN} directly. The error amplifier compares EAP (= $DACQ - I_{SENSE} \times R_{LL}$) with the V_{FB} to regulate the output voltage.

Figure 6. Circuit for V_{OUT} Differential Sensing and No Load Offset

No Load Offset

In Figure 6, I_{OFSN} and I_{OFSP} are used to generate no-load offset. Either I_{OFSN} or I_{OFSP} is active during normal operation. Connect a resistor R_{OFS} between OFS pin and GND to generate negative no-load offset voltage V_{OFSN}.
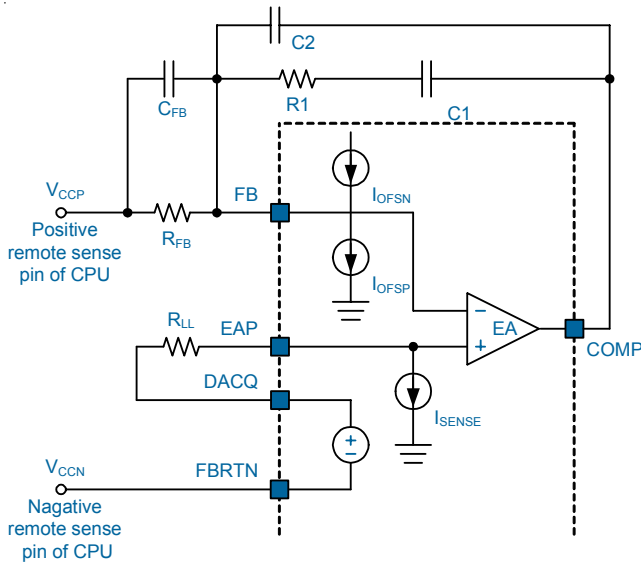
$$V_{OFSN} = I_{OFSN} \times R_{FB} = 1.2 \times R_{FB} / R_{OFS} \qquad (4)$$

Connect a resistor R_{OFS} between OFS pin to V_{CC5} to generate positive no-load offset voltage V_{OFSP}.

$$V_{OFSP} = I_{OFSP} \times R_{FB} = 1.6 \times R_{FB} / R_{OFS} \qquad (5)$$

Load Transient Boost

In steady state, the voltage at VOUT pin V_{VOUT} is higher than V_{TB} by the voltage of $I_{TB} \times R_{TB}$. While a load step transient from light load to heavy load could cause V_{VOUT} temporarily lower than V_{TB}. The uP6208 detects load transient by comparing V_{VOUT} and V_{TB}. If V_{VOUT} drops below V_{TB}. The quick response indicator TB_EN rises up. When TB_EN = High, the uP6208 turns on all high side MOSFETs and turn off all low side MOSFETs. The sensitivity of this transient boost behavior can be adjusted by the values of C_{TB} and R_{TB}. Smaller R_{TB} will make transient boost behavior easier to be triggered while larger C_{FB} will make transient boost behavior sustain longer. Figure 7 is the circuit and typical waveforms.
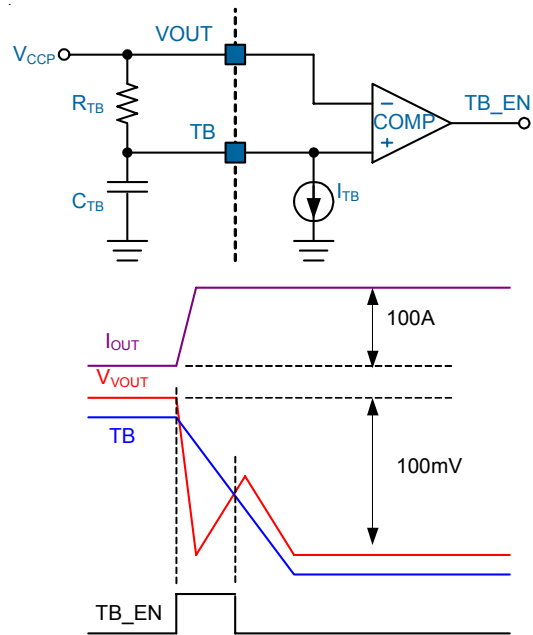
Figure 7. Load Transient Boost

Total Load Current Sensing

The uP6208 provides low input offset current sense amplifier (CSA) to monitor the total load current flowing through inductor as shown in Figure 8. Output current of CSA (I_{SUM}) is used for active voltage positioning (AVP), load current monitoring and over current protection. In this inductor current sensing topology, R_{SW} and C_{SUM} must be selected according to the equation below:

$$R_{SW} \times C_{SUM} = k \times L / R_{DC} \times N \qquad (6)$$

N = Operating Phase Number

Theoretically, k should be equal to 1 to sense the instantaneous total load curret. But in real application usually 1.2 ~ 1.8 is better for transient response.

$$I_{SUM} = I_{L,TOTAL} \times R_{DC} / R_{SUM} / N \qquad (7)$$

In order to minimize to sensing error induced by PCB trace, the PCB trace resistance between V_{CORE12} and inductor 1 should be as equal as possible to the PCB trace resistance between V_{CORE12} and inductor 2. Besides, placement of inductor 1 and inductor 2 should be as close as possible. All other channels should follow these rules also.
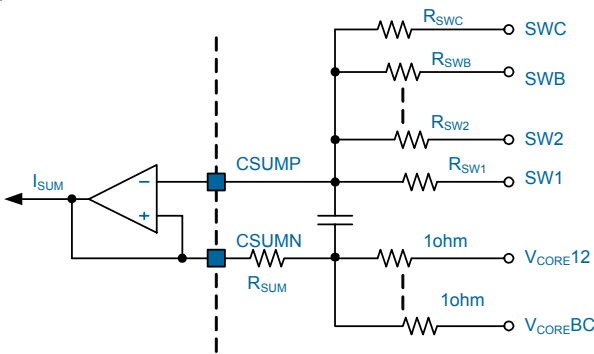
Figure 8. Total Load Current Sensing.

Loadline

I_{SENSE} in Figure 6 is a mirror of I_{SUM} in Figure 8. I_{SENSE} flows through R_{LL} and makes V_{EAP} equal to V_{DACQ} - I_{SENSE} x R_{LL}. In steady state, output voltage is equal to V_{EAP}. Thus, the output voltage decreasing linearly with I_{OUT} is obtained. The loadline is defined as

$$LL(loadline) = \Delta V_{OUT} / \Delta I_{OUT} = R_{DC} \times R_{LL} / R_{CSN} / N \quad (8)$$

Channel Current Sensing

The uP6208 provides low input offset voltage control current source (VCCS) to sense the individual inductor current as shown in Figure 9. Output current of VCCS ($I_{SENSE}[N]$) is used for channel current balance. Unlike prior circuits designed by many other manufacturers that use instantaneous inductor current for both AVP and channel current balance, the uP6208 can use different RC time constant for channel current balance and AVP. Using instantaneous current for AVP is necessary to get good transient response while using instantaneous current for channel current balance is not necessary and may deteriorate transient response and loop stability. It is recommended to select larger RC time constant for channel current balance. That is

$$R_S \times C_S = k \times L/R_{DC}, \ k = 2\text{\textasciitilde}10 \quad (9)$$
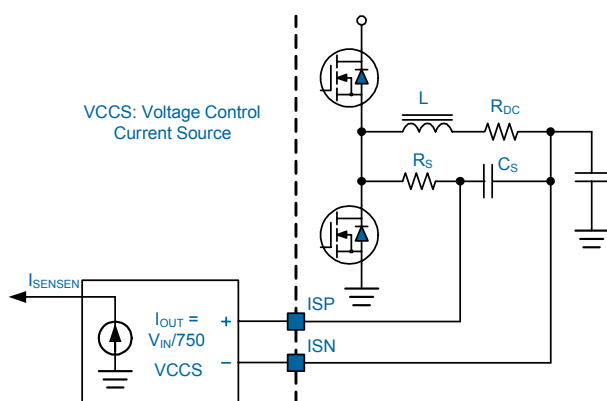
Figure 9. Channel Current Sensing

Current Balance

In Figure 9, $I_{SENSE}[N]$ is the current signal which is proportional to current flowing through channel N. Larger $I_{SENSE}[N]$ will lower the positive input voltage of the corresponding PWM comparator and decrease the PWM duty of the corresponding channel as shown in Figure 10. Eventually, current flowing through each channel will be balanced.
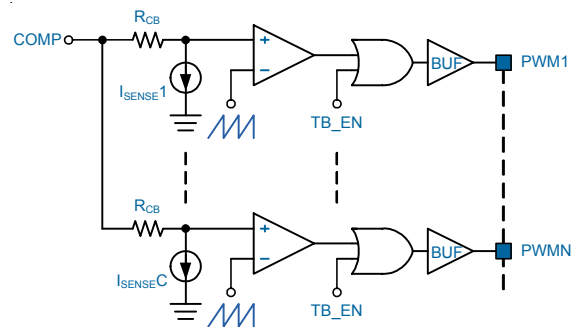
Figure 10. Current Balance

Over Current Protection

The uP6208 provides both channel current OCP and total current OCP as shown in Figure 11. R_{IMAX1} and R_{IMAX2} set the OCP levels respectively. Once OCP is triggered, it will be latched. Only re-start up can release the latch. uP6208 will turn off both high side MOSFET and low side MOSFET of all channels. 20uS delay is used in channel current OCP detection and 80uS delay is use in total current OCP detection to prevent false trigger. It is recommended to use total current OCP as an accurate steady state over current protection while using channel current OCP as short circuit protection.
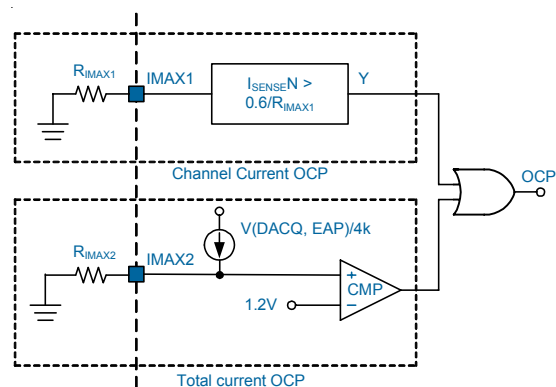
Figure 11. Over Current Protection

Control Loop

A high gain and low input offset error amplifier (EA) is used for the control loop. The positive input of EA is set via the VID logic according to the voltages listed in V_{DAC} table of INTEL VR11/VR10 or AMD K8. This voltage is then shifted by a voltage proportional to total load current for active voltage positioning. The output of the EA is the COMP pin. V_{COMP} is shifted by a voltage proportional to channel current. Then the voltage is compared with internal ramp to generate PWM signal. The negative input (FB) is tied to the positive remote sense pin of CPU through a resistor R_{FB} for sensing and controlling the output voltage. The main loop compensation is incorporated into the feedback network between FB and COMP. A type-3 compensation network like Figure 6 is recommended. The values of R, C in type-3 compensation need complex calculation and fine tune. We simplify the problem by providing a design tool to our customers. Our design tool contains a spreadsheet which can generate the R, C values according to customer's requirement. The design tool does not provide the optimal R, C values but provides a proper starting R, C values for fine tune.

Over Voltage Protection (OVP)

The over voltage protection monitors the output voltage via the VOUT pin. Once V_{VOUT} exceeds V_{EAP} + 150mV, OVP is triggered and latched. The uP6208 will try to turn on low side MOSFET and turn off high side MOSFET to protect CPU. A 20uS delay is used in OVP detection circuit to prevent false trigger. Only re-start up can release OVP latch.

I²C Interface

The uP6208 includes an I²C interface. The main purpose of the I²C interface is to adjust output voltage, switching frequency and operating phase number of VR controller according to the total load current. We call it AUTOPHASE. The target of AUTOPHASE is an optimal VR design for both power conversion efficiency and CPU performance. Operating parameters that can be adjusted through the I²C are:

1. Define the 4 load current states (LCS0, LCS1, LCS2, LCS3): V(IMON) is converted to an 8-bit digital value and compared with 3 I²C programmable registers (VM0[7:0], VM1[7:0], VM2[7:0]). LCS0, LCS1, LCS2 and LCS3 are defined as

   LCS0: V(IMON) > V(VM0[7:0]), highest load current.
   LCS1: V(VM0[7:0]) > V(IMON) > V(VM1[7:0])
   LCS2: V(VM1[7:0]) > V(IMON) > V(VM2[7:0])
   LCS3: V(VM2[7:0]) > V(IMON), lowest load current.

2. Voltage offset of the 4 load current states: 4 I²C pro-

grammable registers (VS0[7:0], VS1[7:0], VS2[7:0], VS3[7:0]) define the voltage offset in LCS0, LCS1, LCS2 and LCS3 respectively.

3. Frequency adjust of the 4 load current states: IICF0[1:0], IICF1[1:0], IICF2[1:0] and IICF3[1:0] define the frequency offset in LCS0, LCS1, LCS2 and LCS3 respectively. F0 is the frequency set by resister between RT pin and GND.

   IICFn[1:0] = [00] => 1.0*F0
   IICFn[1:0] = [01] => 1.2*F0
   IICFn[1:0] = [10] => 1.4*F0
   IICFn[1:0] = [11] => 0.8*F0

4. Operating phase number of the 4 load current states: IICP0[1:0], IICP1[1:0], IICP2[1:0] and IICP3[1:0] define the operating phase number in LCS0, LCS1, LCS2 and LCS3 respectively.

   IICPn[1:0] = [00] => 12-phase
   IICPn[1:0] = [01] => 6-phase
   IICPn[1:0] = [10] => 2-phase
   IICPn[1:0] = [11] => undefined

5. 8-bit A/D conversion result of V(IMON): The result is stored in register IMONAD[7:0]

   V(IMON)=IMON[7:0]*6.25mV
   but IMONAD[7:0] = [11xxxxxx] means V(IMON) > 1.2V only.

6. Read VID input logic value through I²C interface: The value is stored in register IICVID[7:0]

7. Read which VID table is used now through I²C interface: The value is stored in register IICVR[1:0]
   IICVR[1:0] = [00] => AMD 6-bit
   IICVR[1:0] = [01] => AMD 5-bit
   IICVR[1:0] = [10] => VR10
   IICVR[1:0] = [11] => VR11

8. Read operating phase number through I²C interface: The value is stored in register IICP12, IICP6 and IICP2. Always, only one of them is H.

9. Enable/disable the AUTOPHASE function.

Data Validity

The data on the SDA line must be stable during the HIGH period of the SCL, unless generating a START or STOP condition. The HIGH or LOW state of the data line can only change when the clock signal on the SCL line is LOW. Refer to the figure below.

SDA stable / Data Valid   Change of / SDA allowed
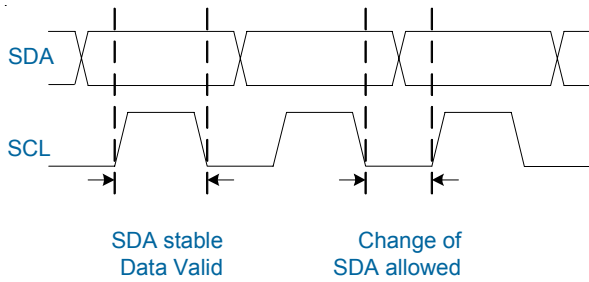
START and STOP Conditions

A START (S) condition is a HIGH to LOW transition of SDA while SCL is HIGH. The STOP (P) condition is a LOW to HIGH transition of SDA while SCL is HIGH. A STOP condition must be sent before each START condition.

START(S)   STOP(P)
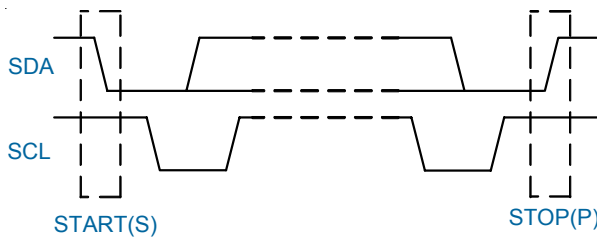
Acknowledge

Each address and data transmission uses 9 clock pulses. The ninth pulse is the acknowledge bit (A). After the start condition, the master sends 7 slave address bits and a R/W bit during the next 8 clock pulses. During the ninth clock pulse, the device that recognizes its own address pulls SDA low to acknowledge. The acknowledge bit is also used by both the master and the slave to acknowledge receipt of register addresses and data.

START(S)   ACK(A)
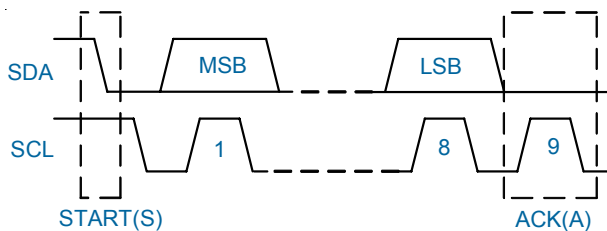
Read and Write Protocol
Write to a Single Register

S	slave_addr+W	AS	reg_addr	AS	reg_data	AS	P

Read from a Single Register

S	slave_addr+W	AS	reg_addr	NA	P

S = START, P = STOP, AS = ACK from slave, AM = ACK from master, NA = No ACK

Register Map

reg_addr	Name	Type	Default value	Description
0x01	VM0[7:0]	R/W	00h	IMON threshold between LCS0 and LCS1, V(IMON) > V(VM0[7:0]) => LCS0 (highest current state)
0x02	VM1[7:0]	R/W	00h	IMON threshold between LCS1 and LCS2, V(VM0[7:0]) > V(IMON) > V(VM1[7:0]) => LCS1
0x03	VM2[7:0]	R/W	00h	IMON threshold between LCS2 and LCS3, V(VM1[7:0]) > V(IMON) > V(VM2[7:0]) => LCS2, V(VM2[7:0]) > V(IMON) => LCS3
0x04	VS0[7:0]	R/W	00h	Voltage offset of LCS0
0x05	VS1[7:0]	R/W	00h	Voltage offset of LCS1
0x06	VS2[7:0]	R/W	00h	Voltage offset of LCS2
0x07	VS3[7:0]	R/W	00h	Voltage offset of LCS3
0x08	IICF0[7:6] IICF1[5:4] IICF2[3:2] IICF3[1:0]	R/W	00h	IICF0[7:6]: freq of LCS0, IICF1[5:4]: freq of LCS1, IICF2[3:2]: freq of LCS2, IICF3[1:0]: freq of LCS3; 00: F0*1.0, 01: F0*1.2, 10: F0*1.4, 11: F0*0.8
0x09	IICP0[7:6] IICP1[5:4] IICP2[3:2] IICP3[1:0]	R/W	00h	IICP0[7:6]: phase number of LCS0, IICP1[5:4]: phase number of LCS1, IICP2[3:2]: phase number of LCS2, IICP3[1:0]: phase number of LCS3; 00: 12 phase, 01: 6 phase, 10: 2 phase, 11: 12 phase(reverved)
0x0A	IMONAD[7:0]	R	xxh	V(IMON)=IMON[7:0]*6.25mV, max=1.2V
0x0B	IICVID[7:0]	R	xxh	Read VID input pin
0x0C	IICVR[7:6] IICP12[5] IICP6[4] IICP2[3]	R	xxh	Read VR table; IICVR[7:6] = 11 => VR11, IICVR[7:6] = 10 => VR10, IICVR[7:6] = 01 => K8, IICVR[7:6] = 00 => K9 IICP12[5]=1 => 12 phase, IICP6[4]=1 => 6 phase, IICP2[3]=1 => 2 phase
0x0D	AUOTPHS xxxx TGLPOC[2:0]	R/W	00h	AUOTPHS: Enable auto_phase, TGLPOC[2]: toggle POC[2], TGLPOC[1]: toggle POC[1], TGLPOC[0]: toggle POC[0]
0x0E	MISC[7:4]	R/W	0x00xxxx	MISC[7]:Enable watch dog timer, MISC[6]: Watching Dog timer (If time-out set to 1, cleared after reading, read only), MISC[5:4]: 11=>3200mS, 10=>1600mS, 01=>800mS, 00=>400mS default 0x00
0x0F	VER[3:0]	R	11h	Version
0XB2	CHIPID[7:0]	R	01h	Chip ID

Functional Description

VSN[7:0]

bit7	bit6	bit5	bit4	bit3	bit2	bit1	bit0	Voffset(mv)	bit7	bit6	bit5	bit4	bit3	bit2	bit1	bit0	Voffset(mv)
1	0	0	0	0	0	0	0	0.00	1	0	1	0	1	0	1	1	268.75
1	0	0	0	0	0	0	1	6.25	1	0	1	0	1	1	0	0	275.00
1	0	0	0	0	0	1	0	12.50	1	0	1	0	1	1	0	1	281.25
1	0	0	0	0	0	1	1	18.75	1	0	1	0	1	1	1	0	287.50
1	0	0	0	0	1	0	0	25.00	1	0	1	0	1	1	1	1	293.75
1	0	0	0	0	1	0	1	31.25	1	0	1	1	0	0	0	0	300.00
1	0	0	0	0	1	1	0	37.50	1	0	1	1	0	0	0	1	306.25
1	0	0	0	0	1	1	1	43.75	1	0	1	1	0	0	1	0	312.50
1	0	0	0	1	0	0	0	50.00	1	0	1	1	0	0	1	1	318.75
1	0	0	0	1	0	0	1	56.25	1	0	1	1	0	1	0	0	325.00
1	0	0	0	1	0	1	0	62.50	1	0	1	1	0	1	0	1	331.25
1	0	0	0	1	0	1	1	68.75	1	0	1	1	0	1	1	0	337.50
1	0	0	0	1	1	0	0	75.00	1	0	1	1	0	1	1	1	343.75
1	0	0	0	1	1	0	1	81.25	1	0	1	1	1	0	0	0	350.00
1	0	0	0	1	1	1	0	87.50	1	0	1	1	1	0	0	1	356.25
1	0	0	0	1	1	1	1	93.75	1	0	1	1	1	0	1	0	362.50
1	0	0	1	0	0	0	0	100.00	1	0	1	1	1	0	1	1	368.75
1	0	0	1	0	0	0	1	106.25	1	0	1	1	1	1	0	0	375.00
1	0	0	1	0	0	1	0	112.50	1	0	1	1	1	1	0	1	381.25
1	0	0	1	0	0	1	1	118.75	1	0	1	1	1	1	1	0	387.50
1	0	0	1	0	1	0	0	125.00	1	0	1	1	1	1	1	1	393.75
1	0	0	1	0	1	0	1	131.25	1	1	0	0	0	0	0	0	400.00
1	0	0	1	0	1	1	0	137.50	1	1	0	0	0	0	0	1	406.25
1	0	0	1	0	1	1	1	143.75	1	1	0	0	0	0	1	0	412.50
1	0	0	1	1	0	0	0	150.00	1	1	0	0	0	0	1	1	418.75
1	0	0	1	1	0	0	1	156.25	1	1	0	0	0	1	0	0	425.00
1	0	0	1	1	0	1	0	162.50	1	1	0	0	0	1	0	1	431.25
1	0	0	1	1	0	1	1	168.75	1	1	0	0	0	1	1	0	437.50
1	0	0	1	1	1	0	0	175.00	1	1	0	0	0	1	1	1	443.75
1	0	0	1	1	1	0	1	181.25	1	1	0	0	1	0	0	0	450.00
1	0	0	1	1	1	1	0	187.50	1	1	0	0	1	0	0	1	456.25
1	0	0	1	1	1	1	1	193.75	1	1	0	0	1	0	1	0	462.50
1	0	1	0	0	0	0	0	200.00	1	1	0	0	1	0	1	1	468.75
1	0	1	0	0	0	0	1	206.25	1	1	0	0	1	1	0	0	475.00
1	0	1	0	0	0	1	0	212.50	1	1	0	0	1	1	0	1	481.25
1	0	1	0	0	0	1	1	218.75	1	1	0	0	1	1	1	0	487.50
1	0	1	0	0	1	0	0	225.00	1	1	0	0	1	1	1	1	493.75
1	0	1	0	0	1	0	1	231.25	1	1	0	1	0	0	0	0	500.00
1	0	1	0	0	1	1	0	237.50	1	1	0	1	0	0	0	1	501.25
1	0	1	0	0	1	1	1	243.75	1	1	0	1	0	0	1	0	512.50
1	0	1	0	1	0	0	0	250.00	1	1	0	1	0	0	1	1	518.75
1	0	1	0	1	0	0	1	256.25	1	1	0	1	0	1	0	0	525.00
1	0	1	0	1	0	1	0	262.50	1	1	0	1	0	1	0	1	531.25

Functional Description

bit7	bit6	bit5	bit4	bit3	bit2	bit1	bit0	Voffset(mv)	bit7	bit6	bit5	bit4	bit3	bit2	bit1	bit0	Voffset(mv)
1	1	0	1	0	1	1	0	537.50	0	0	0	0	0	0	0	1	-6.25
1	1	0	1	0	1	1	1	543.75	0	0	0	0	0	0	1	0	-12.50
1	1	0	1	1	0	0	0	550.00	0	0	0	0	0	0	1	1	-18.75
1	1	0	1	1	0	0	1	556.25	0	0	0	0	0	1	0	0	-25.00
1	1	0	1	1	0	1	0	562.50	0	0	0	0	0	1	0	1	-31.25
1	1	0	1	1	0	1	1	568.75	0	0	0	0	0	1	1	0	-37.50
1	1	0	1	1	1	0	0	575.00	0	0	0	0	0	1	1	1	-43.75
1	1	0	1	1	1	0	1	581.25	0	0	0	0	1	0	0	0	-50.00
1	1	0	1	1	1	1	0	587.50	0	0	0	0	1	0	0	1	-56.25
1	1	0	1	1	1	1	1	593.75	0	0	0	0	1	0	1	0	-62.50
1	1	1	0	0	0	0	0	600.00	0	0	0	0	1	0	1	1	-68.75
1	1	1	0	0	0	0	1	606.25	0	0	0	0	1	1	0	0	-75.00
1	1	1	0	0	0	1	0	612.50	0	0	0	0	1	1	0	1	-81.25
1	1	1	0	0	0	1	1	618.75	0	0	0	0	1	1	1	0	-87.50
1	1	1	0	0	1	0	0	625.00	0	0	0	0	1	1	1	1	-93.75
1	1	1	0	0	1	0	1	631.25	0	0	0	1	0	0	0	0	-100.00
1	1	1	0	0	1	1	0	637.50	0	0	0	1	0	0	0	1	-106.25
1	1	1	0	0	1	1	1	643.75	0	0	0	1	0	0	1	0	-112.50
1	1	1	0	1	0	0	0	650.00	0	0	0	1	0	0	1	1	-118.75
1	1	1	0	1	0	0	1	656.25	0	0	0	1	0	1	0	0	-125.00
1	1	1	0	1	0	1	0	662.50	0	0	0	1	0	1	0	1	-131.25
1	1	1	0	1	0	1	1	668.75	0	0	0	1	0	1	1	0	-137.50
1	1	1	0	1	1	0	0	675.00	0	0	0	1	0	1	1	1	-143.75
1	1	1	0	1	1	0	1	681.25	0	0	0	1	1	0	0	0	-150.00
1	1	1	0	1	1	1	0	687.50	0	0	0	1	1	0	0	1	-156.25
1	1	1	0	1	1	1	1	693.75	0	0	0	1	1	0	1	0	-162.50
1	1	1	1	0	0	0	0	700.00	0	0	0	1	1	0	1	1	-168.75
1	1	1	1	0	0	0	1	706.25	0	0	0	1	1	1	0	0	-175.00
1	1	1	1	0	0	1	0	712.50	0	0	0	1	1	1	0	1	-181.25
1	1	1	1	0	0	1	1	718.75	0	0	0	1	1	1	1	0	-187.50
1	1	1	1	0	1	0	0	725.00	0	0	0	1	1	1	1	1	-193.75
1	1	1	1	0	1	0	1	731.25	0	0	1	0	0	0	0	0	-200.00
1	1	1	1	0	1	1	0	737.50	0	0	1	0	0	0	0	1	-206.25
1	1	1	1	0	1	1	1	743.75	0	0	1	0	0	0	1	0	-212.50
1	1	1	1	1	0	0	0	750.00	0	0	1	0	0	0	1	1	-218.75
1	1	1	1	1	0	0	1	756.25	0	0	1	0	0	1	0	0	-225.00
1	1	1	1	1	0	1	0	762.50	0	0	1	0	0	1	0	1	-231.25
1	1	1	1	1	0	1	1	768.75	0	0	1	0	0	1	1	0	-237.50
1	1	1	1	1	1	0	0	775.00	0	0	1	0	0	1	1	1	-243.75
1	1	1	1	1	1	0	1	781.25	0	0	1	0	1	0	0	0	-250.00
1	1	1	1	1	1	1	0	787.50	0	0	1	0	1	0	0	1	-256.25
1	1	1	1	1	1	1	1	793.75	0	0	1	0	1	0	1	0	-262.50
0	0	0	0	0	0	0	0	0.00	0	0	1	0	1	0	1	1	-268.75

Functional Description

bit7	bit6	bit5	bit4	bit3	bit2	bit1	bit0	Voffset(mv)
0	0	1	0	1	1	0	0	-275.00
0	0	1	0	1	1	0	1	-281.25
0	0	1	0	1	1	1	0	-287.50
0	0	1	0	1	1	1	1	-293.75
0	0	1	1	0	0	0	0	-300.00
0	0	1	1	0	0	0	1	-306.25
0	0	1	1	0	0	1	0	-312.50
0	0	1	1	0	0	1	1	-318.75
0	0	1	1	0	1	0	0	-325.00
0	0	1	1	0	1	0	1	-331.25
0	0	1	1	0	1	1	0	-337.50
0	0	1	1	0	1	1	1	-343.75
0	0	1	1	1	0	0	0	-350.00
0	0	1	1	1	0	0	1	-356.25
0	0	1	1	1	0	1	0	-362.50
0	0	1	1	1	0	1	1	-368.75
0	0	1	1	1	1	0	0	-375.00
0	0	1	1	1	1	0	1	-381.25
0	0	1	1	1	1	1	0	-387.50
0	0	1	1	1	1	1	1	-393.75
0	1	0	0	0	0	0	0	-400.00
0	1	0	0	0	0	0	1	-406.25
0	1	0	0	0	0	1	0	-412.50
0	1	0	0	0	0	1	1	-418.75
0	1	0	0	0	1	0	0	-425.00
0	1	0	0	0	1	0	1	-431.25
0	1	0	0	0	1	1	0	-437.50
0	1	0	0	0	1	1	1	-443.75
0	1	0	0	1	0	0	0	-450.00
0	1	0	0	1	0	0	1	-456.25
0	1	0	0	1	0	1	0	-462.50
0	1	0	0	1	0	1	1	-468.75
0	1	0	0	1	1	0	0	-475.00
0	1	0	0	1	1	0	1	-481.25
0	1	0	0	1	1	1	0	-487.50
0	1	0	0	1	1	1	1	-493.75
0	1	0	1	0	0	0	0	-500.00
0	1	0	1	0	0	0	1	-506.25
0	1	0	1	0	0	1	0	-512.50
0	1	0	1	0	0	1	1	-518.75
0	1	0	1	0	1	0	0	-525.00
0	1	0	1	0	1	0	1	-531.25

bit7	bit6	bit5	bit4	bit3	bit2	bit1	bit0	Voffset(mv)
0	1	0	1	0	1	1	0	-537.50
0	1	0	1	0	1	1	1	-543.75
0	1	0	1	1	0	0	0	-550.00
0	1	0	1	1	0	0	1	-556.25
0	1	0	1	1	0	1	0	-562.50
0	1	0	1	1	0	1	1	-568.75
0	1	0	1	1	1	0	0	-575.00
0	1	0	1	1	1	0	1	-581.25
0	1	0	1	1	1	1	0	-587.50
0	1	0	1	1	1	1	1	-593.75
0	1	1	0	0	0	0	0	-600.00
0	1	1	0	0	0	0	1	-606.25
0	1	1	0	0	0	1	0	-612.50
0	1	1	0	0	0	1	1	-618.75
0	1	1	0	0	1	0	0	-625.00
0	1	1	0	0	1	0	1	-631.25
0	1	1	0	0	1	1	0	-637.50
0	1	1	0	0	1	1	1	-643.75
0	1	1	0	1	0	0	0	-650.00
0	1	1	0	1	0	0	1	-656.25
0	1	1	0	1	0	1	0	-662.50
0	1	1	0	1	0	1	1	-668.75
0	1	1	0	1	1	0	0	-675.00
0	1	1	0	1	1	0	1	-681.25
0	1	1	0	1	1	1	0	-687.50
0	1	1	0	1	1	1	1	-693.75
0	1	1	1	0	0	0	0	-700.00
0	1	1	1	0	0	0	1	-706.25
0	1	1	1	0	0	1	0	-712.50
0	1	1	1	0	0	1	1	-718.75
0	1	1	1	0	1	0	0	-725.00
0	1	1	1	0	1	0	1	-731.25
0	1	1	1	0	1	1	0	-737.50
0	1	1	1	0	1	1	1	-743.75
0	1	1	1	1	0	0	0	-750.00
0	1	1	1	1	0	0	1	-756.25
0	1	1	1	1	0	1	0	-762.50
0	1	1	1	1	0	1	1	-768.75
0	1	1	1	1	1	0	0	-775.00
0	1	1	1	1	1	0	1	-781.25
0	1	1	1	1	1	1	0	-787.50
0	1	1	1	1	1	1	1	-793.75

Absolute Maximum Rating

Supply Input Voltage, 5VCC (Note 1) --- -0.3V to +6V
Other Pins -- -0.3V to +6V
Storage Temperature Range --- -65°C to +150°C
Junction Temperature -- 150°C
Lead Temperature (Soldering, 10 sec) --- 260°C
ESD Rating (Note 2)
　　HBM (Human Body Mode) --- 2kV
　　MM (Machine Mode) -- 200V

Thermal Information

Package Thermal Resistance (Note 3)
　　LQFP7x7 - 64L θ_{JA} --- TBD
Power Dissipation, P_D @ TA = 25°C
　　LQFP7x7 - 64L θ_{JA} --- TBD

Recommended Operation Conditions

Operating Junction Temperature Range (Note 4) -- -40°C to +125°C
Operating Ambient Temperature Range -- -40°C to +85°C
Supply Input Voltage, V_{CC5} -- 4.5V to 5.5V

Electrical Characteristics

(5VCC = 5V, T_A = 25°C, unless otherwise specified)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Units
Supply Input						
Supply Input Voltage	V_{CC5}		4.5	--	5.5	V
V_{CC5} POR Threshold			4.1	4.3	4.5	V
V_{CC5} POR Hysteresis		5VCC Falling.	--	0.1	--	V
Supply Current	I_{CC5}	No Switching	--	6	--	mA
Error Amplifier						
Offset Voltage	$V_{OS(EA)}$		-1	--	1	mV
Input Bias Current	I_{EA}		-10	--	10	nA
Gain Bandwidth Product	GBW_{EA}		--	10	--	MHz
Voltage Accuracy						
DAC Output Accuracy	V_{FB}	1.0V to 1.6V	-0.5	--	0.5	%
		0.8V to 1.0V	-8	--	8	mV
		0.5V to 0.8V	-10	--	10	mV
Soft Start						
Soft Start Current	I_{SS}	Normal	--	32	--	uA
VTT Input						
Input Low	$V_{IL(VTT)}$		--	0.75	--	V
Input High	$V_{IH(VTT)}$		--	0.85	--	V

Parameter	Symbol	Test Conditions	Min	Typ	Max	Units
VTT Input						
Input Current	I_{VTT}		-3	--	3	uA
EN Input						
Input Low	$V_{ILEN)}$		--	1	--	V
Input High	$V_{IH(EN)}$		--	1.1	--	V
Input Curent	I_{EN}		-1	--	1	uA
VID Input						
Input Low	$V_{IL(VID)}$	VTT = 1.2V	0.5	--	--	V
Input High	$V_{IH(VID)}$	VTT = 1.2V	--	--	0.7	V
Input Curent	I_{VID}		-1	--	1	uA
VIDOFF Delay Time	T_{VIDOFF}		--	20	--	us
Oscillator						
Frequency Range	F_{SW}		100	--	1000	kHz
Frequency Variation		R_{RT} = 26kΩ	270	300	330	kHz
Max Duty		R_{RT} = 26kΩ	--	50	--	%
Output Voltage	V_{RT}		0.75	0.80	0.85	V
Current Sense Amplifier						
Offset Voltage	$V_{OS(CSA)}$	No Load, Guaranteed by Design	-1	--	1	mV
Input Bias Current			-10	--	10	nA
Gain Bandwidth Product	$G_{BW(CSA)}$		--	10	--	MHz
Current Balance VCCS						
Offset Voltage	$V_{OS(VCCS)}$		-2	--	2	mV
Transconductance	GM_{VCC5}		--	1.33-E-03	--	1/Ω
Gain Bandwidth Product	$G_{BW(VCCS)}$		--	10	--	MHz
PWM Output						
Output Low Voltage	$V_{OL(PWM)}$	I_{SINK} = 4mA	--	--	0.2	V
Output High Voltage	$V_{OH(PWM}$	I_{SOURCE} = 4mA	4.7	--	--	V
PWRGD Ouput						
Output Low Voltage	$V_{OL(PWRGD)}$	I_{SINK} = 4mA	--	--	0.2	V
Current Monitoring						
IMON Output Voltage			--	--	1.1	V
IMON Voltage Variation		Full Load	-10	--	10	%

Electrical Characteristics

Parameter	Symbol	Test Conditions	Min	Typ	Max	Units
Protection						
OVP Threshold	V_{OVP}	VOUT-VEAP	--	150	--	mV
OVP Dealy	T_{OVP}		--	20	--	us
IMAX1 Output Voltage			1.15	1.20	1.25	V
Channel Current OCP Daly	T_{OCP1}		--	20	--	us
IMAX Input Threshold			1.15	1.20	1.25	V
Total Current OCP Dealy	T_{OCP2}		--	20	--	us

Note 1. Stresses listed as the above "Absolute Maximum Ratings" may cause permanent damage to the device. These are for stress ratings. Functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may remain possibility to affect device reliability.

Note 2. Devices are ESD sensitive. Handling precaution recommended.

Note 3. θ_{JA} is measured in the natural convection at T_A = 25°C on a low effective thermal conductivity test board of JEDEC 51-3 thermal measurement standard.

Note 4. The device is not guaranteed to function outside its operating conditions.

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Package Information

9.00 BSC
7.00 BSC
48
33
49
32
9.00 BSC
7.00 BSC
64
17
1
16
0.40 BSC
0.13 - 0.23

0.09 - 0.20

0.60 BSC

0.25 REF
1.60 MAX
1.00 BSC
0.05 - 0.15
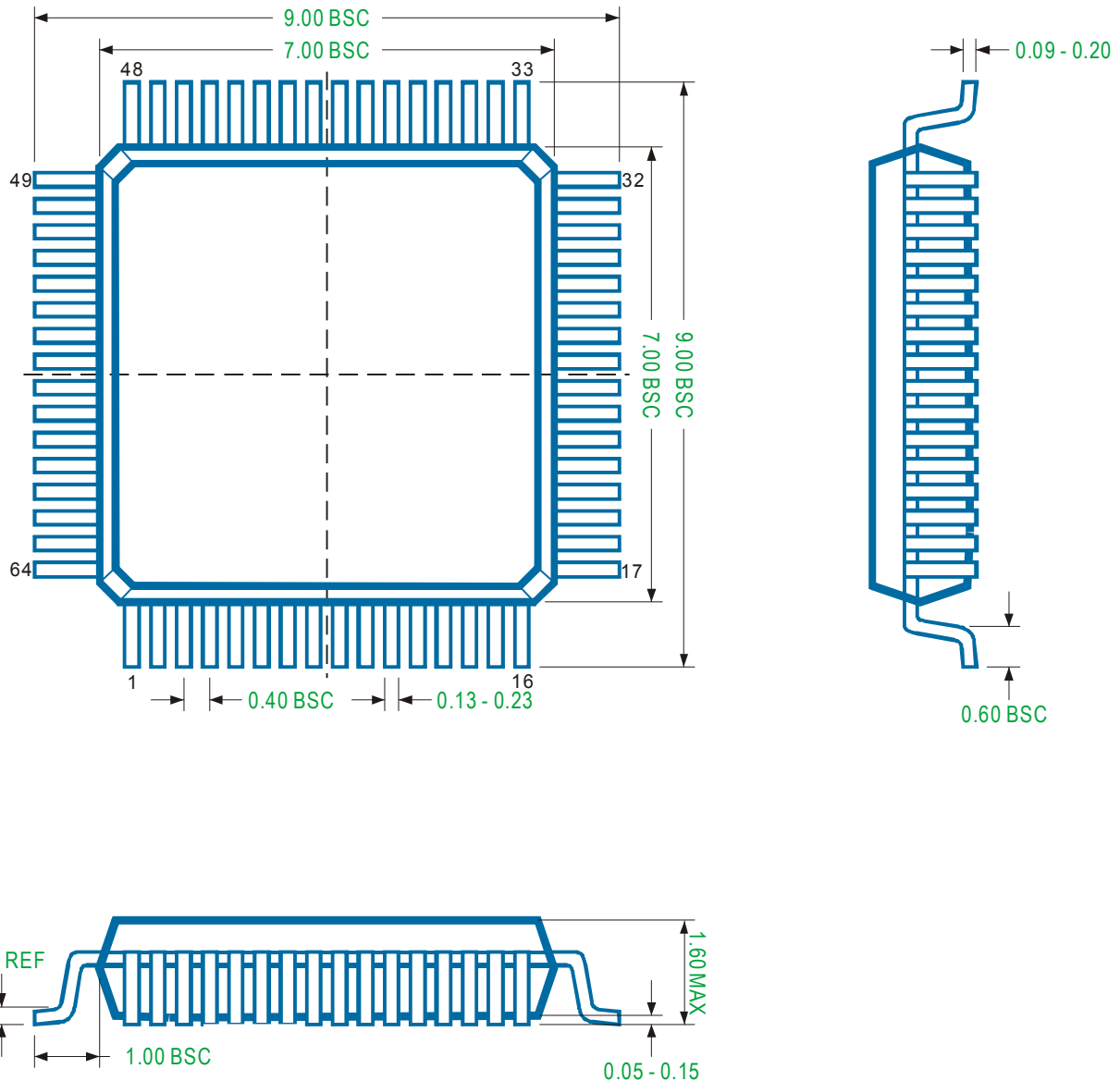
Note
1. Package Outline Unit Description:
   BSC: Basic. Represents theoretical exact dimension or dimension target
   MIN: Minimum dimension specified.
   MAX: Maximum dimension specified.
   REF: Reference. Represents dimension for reference use only. This value is not a device specification.
   TYP. Typical. Provided as a general value. This value is not a device specification.
2. Dimensions in Millimeters.
3. Drawing not to scale.
4. These dimensions no not include mold flash or protrusions. Mold flash or protrusions shell not exceed 0.15mm.